



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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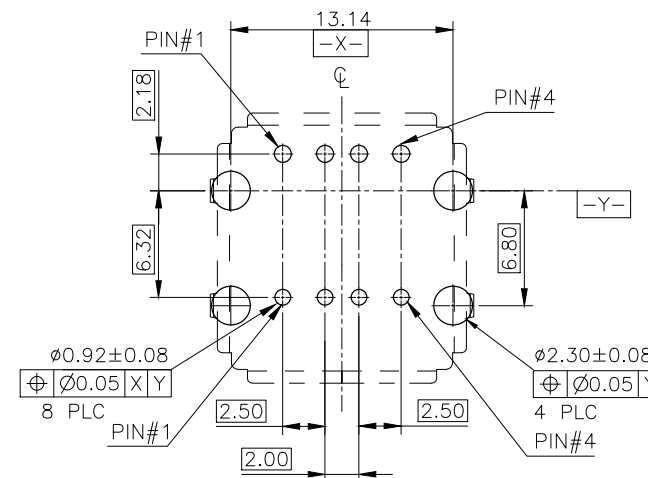
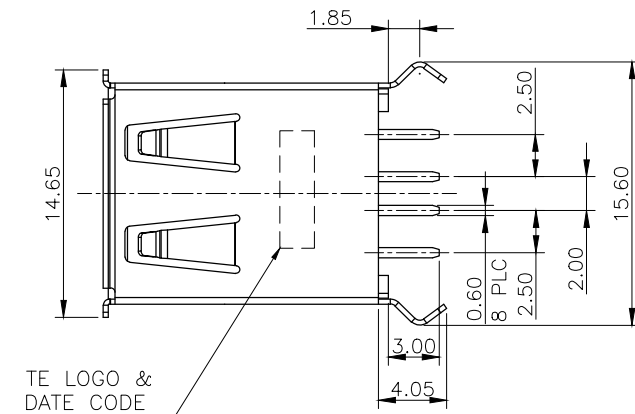
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LOC DW

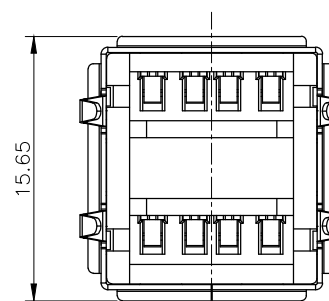
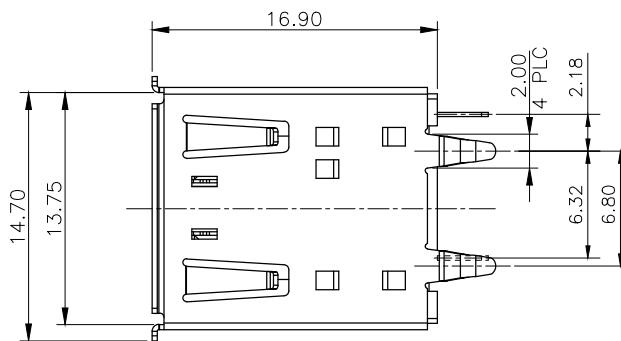
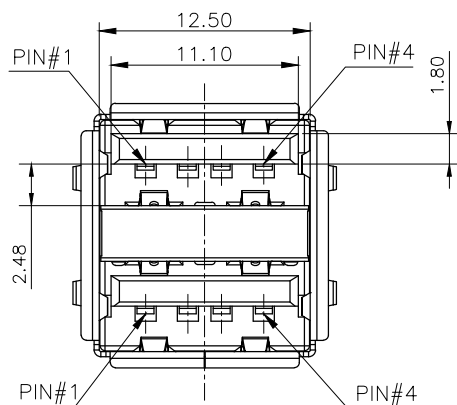
DIST

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
B3		REVISED (ECR-14-006687)	05FEB15	S.C	H.L



RECOMMEND P.C.B LAYOUT THICKNESS=1.6mm
(COMPONENT SIDE) TOLERANCES:0.05mm



NOTES:

- MATERIAL:
HOUSING: (SEE TABLE) WITH 30% GF, UL 94V-0, BLACK COLOR
CONTACT: BRASS, (t=0.25±0.05mm).
SHIELD: BRASS, (t=0.30±0.05mm).
GROUNDING STRIP: SUS. (T=0.20±0.05mm).
- FINISH :
CONTACT: (SEE TABLE) GOLD PLATING ON CONTACT AREA,
3.048µm [120µ"] MIN. BRIGHT TIN PLATING ON SOLDER TAILS
1.27µm [50µ"] MIN. NICKEL UNDERPLATING ALL OVER.
SHIELD: 0.762µm [30µ"] MIN. NICKEL PLATING OVER
2.54µm [100µ"] MIN Cu.
- WAVE SOLDER CAPABLE TO 265°C PER TEST SPEC.
109-202, CONDITION B.
- REFLOW SOLDER CAPABLE TO 260°C PER TE CONNECTIVITY TEST SPEC.
109-201, CONDITION B.

5 OBSOLETE PARTS

PA9T	△ 50µ"	△ 51-1775066-3
	△ 30µ"	△ 51-1775066-2
	△ G/F	1-1775066-1
PBT	△ 50µ"	1775066-3
	△ 30µ"	△ 51-1775066-2
	△ G/F	1775066-1
HSG. MATERIAL	GOLD PLATING	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN F. YANG 20MAR2009	STE TE Connectivity	
DIMENSIONS: MM		CHK S. CHIEN 20MAR2009		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD W. KODAMA 20MAR2009	NAME	
0 PLC ± -		PRODUCT SPEC		USB CONNECTOR, STACKED, VERTICAL, DIP, A TYPE
1 PLC ± 0.25		108-57505		
2 PLC ± 0.20		QUALIFICATION TEST REPORT		
3 PLC ± -		501-57611		
4 PLC ± -		SIZE A3	CAGE CODE 00779	DRAWING NO C=1775066
ANGLES ± 3'		WEIGHT 4.57 GRAMS	RESTRICTED TO	
MATERIAL SEE NOTE	FINISH SEE NOTE	CUSTOMER DRAWING		SCALE
		SHEET 1 of 2		REV B3

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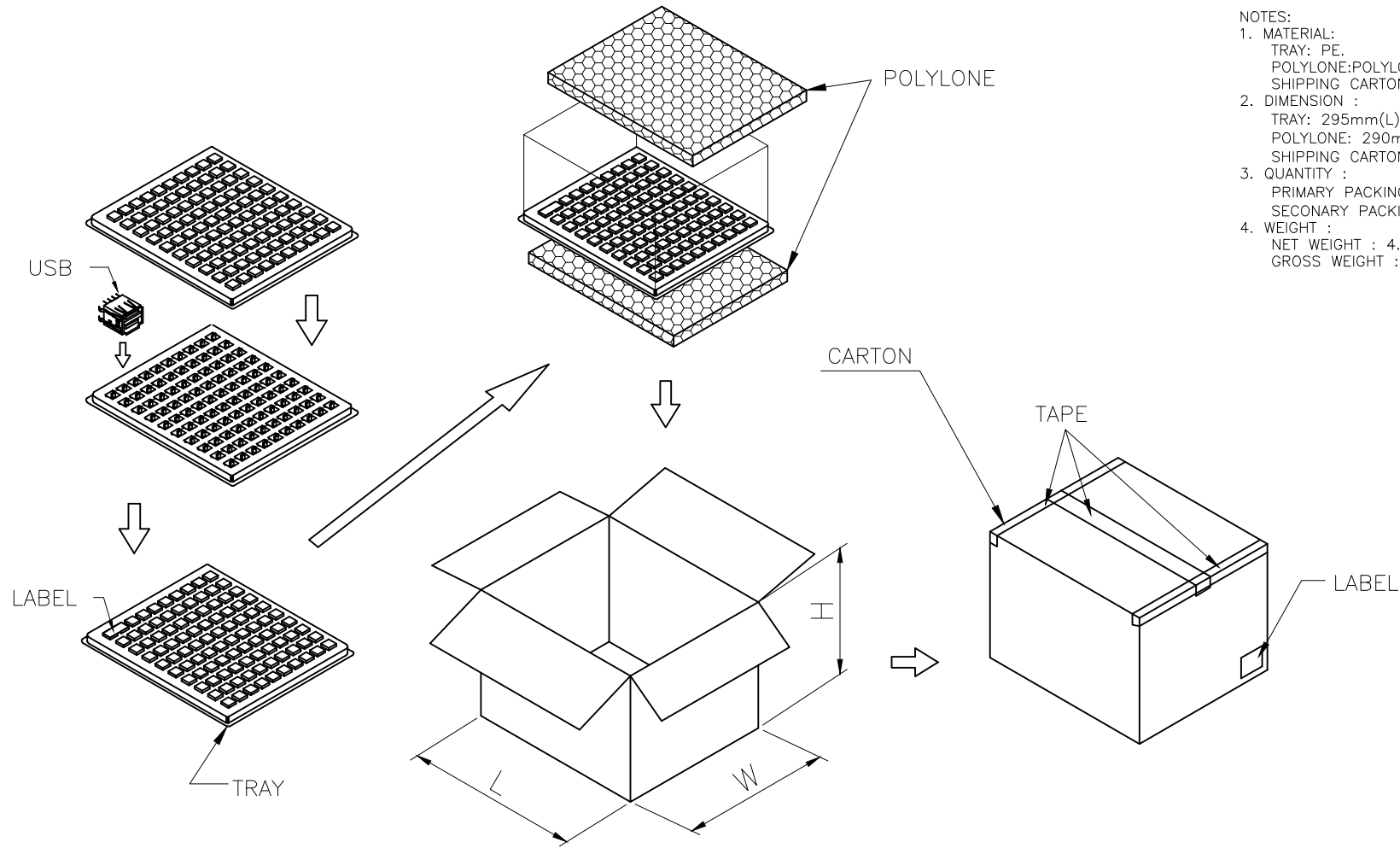
DIST

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
-		SEE SHEET 1			

NOTES:

- MATERIAL:
TRAY: PE.
POLYLONE: POLYLONE
SHIPPING CARTON: CORRUGATED FIBER.
- DIMENSION :
TRAY: 295mm(L)X 255mm(W)X 19mm(H)
POLYLONE: 290mm(L)X 250mm(W)X 20mm(H)
SHIPPING CARTON: 315mm(L)X 260mm(W)X 220mm(H)
- QUANTITY :
PRIMARY PACKING: 100 PCS/TRAY
SECONDARY PACKING: 10 TRAYS/CARTON(1000PCS).
- WEIGHT :
NET WEIGHT : 4.57 KG
GROSS WEIGHT : 6.63 KG



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DIMENSIONS: MM		CHK		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD	NAME	
0 PLC ± -		PRODUCT SPEC	USB CONNECTOR, STACKED, VERTICAL, DIP, A TYPE	
1 PLC ± -		QUALIFICATION TEST REPORT	SIZE	RESTRICTED TO
2 PLC ± -		WEIGHT	A3	
3 PLC ± -		CUSTOMER DRAWING	CAGE CODE	DRAWING NO
4 PLC ± -			00779	C=1775066
ANGLES ± -			SCALE	SHEET 2 of 2
MATERIAL SEE NOTE	FINISH SEE NOTE			REV B3